The most important thing we build is trust

TRUSTED ACCREDITATION
Aeroflex Colorado Springs (Cobham) received Category 1A Trusted Accreditation by the Defense Microelectronics Activity as a Microelectronics Trusted Source for DoD and all other U.S. government users. The scope of accreditation includes:

- Design, Packaging /Assembly, Test and Aggregation/Brokering of multi-project-wafers into Trusted Foundries.

Cobham offers:
- Trusted foundry access with ASIC Design Services for radiation hardened and non-hardened program applications
  - IBM - 90nm
  - ON Semiconductor - 0.6μm
- One stop solution for your integrated assembly, evaluation, test and screening requirements
- Quick-turn capabilities available
- QML Q and QML V flows, MIL-PRF-38535 compliant, ISO-9001 certified
- Element evaluation
- Certified known good die program available
- Value-added services such as radiation testing, secure testing and COTS/commercial upscreening
- Class 100, 5100 sq. ft. Clean Room
- Analytical and DPA services

SPECIALIZED SERVICES
- Customer Furnished Tooling - Cobham has experience in assembling customer originated die, packages, test and screening requirements into a smooth, seamless high quality process.
- Radiation Testing - Cobham RAD offers a comprehensive commercial radiation effects testing based in the US and UK. From Total Ionizing Dose (TID) test to complex Single Events Effects (SEE) tests, complete turnkey services are available. DSCC/DLA suitability for radiation test methods 1019, 1017, 1020, 1021.
- Secure Testing - Cobham has tested parts in a secure environment for classified programs for over 27 years. The facility and employees have the necessary clearances and the proper training.
- COTS/Commercial Upscreening - Cobham’s experience in the high-reliability marketplace allows us to perform additional testing and burn-in to your commercial parts to meet customized military requirements.
- Space Qualified Assembly Services - Cobham is a DLA certified QML V manufacturer of space qualified ICs.

PRODUCTION CAPABILITIES
Cobham can provide a complete solution for your integrated assembly, evaluation, test and screening requirements.

- Assembly
  - Wafer Backgrind
  - Wafer Saw
  - Assembly and Wirebond State-of-the art wirebonding; 60 mil pitch available
  - Hermetic packages available
  - LCC, PGA, QFP, DIP, FP, Multi-chip modules
  - Solder Dip -- Meets MIL-STD-883, Method 2003
  - Internal Visual Meets MIL-STD-883, Method 2010, Cond A or B

- Burn-In Services
  - Static/Dynamic Burn-in
  - Accelerated Life Test

- Electrical Test
  - Wafer Level DC Parametrics
  - Memory, Logic and Analog IC Testing
  - Wafer Probe and Package IC Testing
  - High and Low Temperature IC Testing
  - Teradyne Testers with 1024 digital pins and frequencies up to 800 MHz

- Environmental Test
  - Hermeticity Meets MIL-STD-883, Method 1014, Cond A1, A2, C3
  - PIND Meets MIL-STD-883, Method 2020, Cond A, B
  - Temp Cycle Meets MIL-STD-883, Method 1010, Cond A, B, C, D or F

- Failure Analysis diagnostic capability the transistor level.
  - EDS, SEM, E-Beam, DPA
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